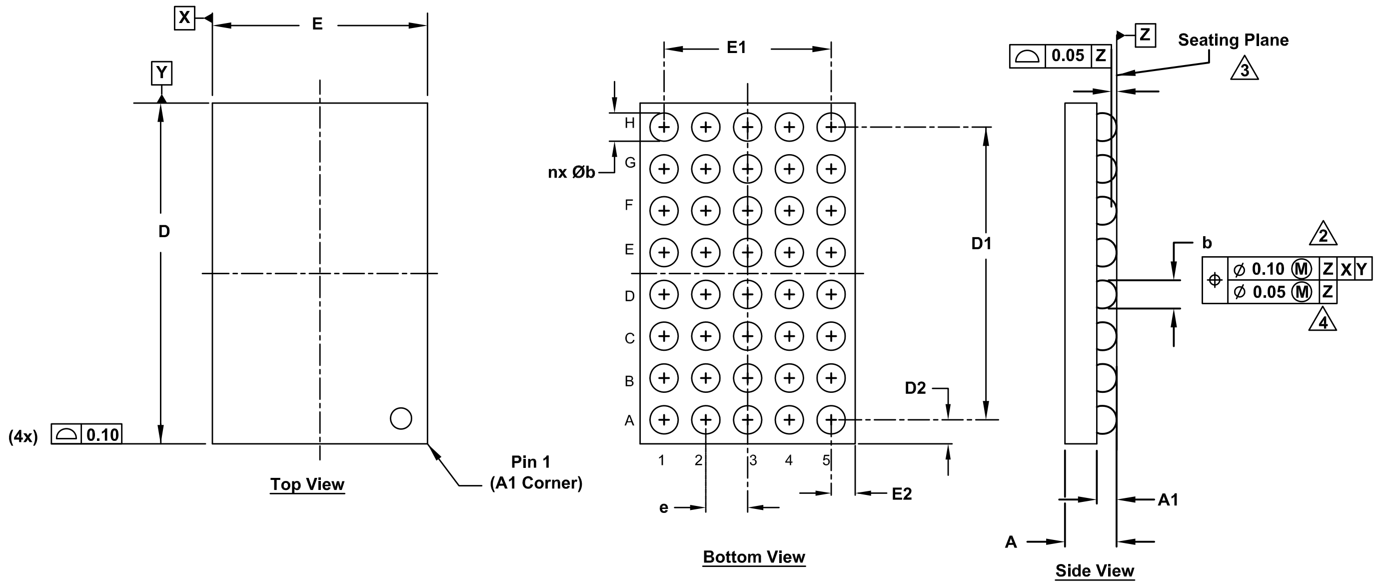
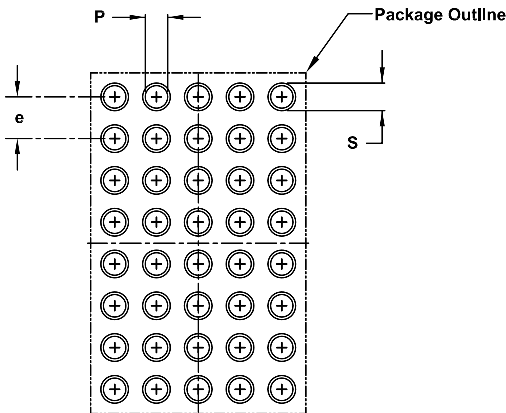
Package Outline Drawing

W5x8.40A
40 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)
Rev 2, 2/20





		Symbol	Min	Nom	Max
Total Thickness		A	0.45	0.50	0.55
Stand Off		A1	0.17	0.20	0.23
Body Size	X	E	2.03	2.06	2.09
	Y	D	3.23	3.26	3.29
Edge Ball Center to Center	X	E1		1.60	
	Y	D1		2.80	
Edge Ball Center to Package Edge	X	E2		0.23	
	Y	D2		0.23	
Pitch		e		0.4 BSC	
Ball Diameter (Size)				0.25	
Ball Width		b	0.230	0.265	0.300
Ball Count		n		40	
PCB Pad Diameter		P		0.215	
PCB Soldermask Opening		S		0.265	

Notes:

1. Dimensions and tolerance per ASME Y14.5 - 1994.
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
6. NSMD refers to non-solder mask defined pad design per Renesas TB451.